

ABSTRACT

Method of processing a workpiece, and a work carrier, in particular of porous ceramic

Explained, *inter alia*, is a method in which a workpiece (52) to be processed is fastened to a work carrier (10) by means of a solid (62). The work carrier (10) is made of a porous material, e.g. of porous ceramic. This processing method permits simple manipulation of the wafer during the processing. In addition, the workpiece (52) can be easily separated from the work carrier (10) using a solvent.